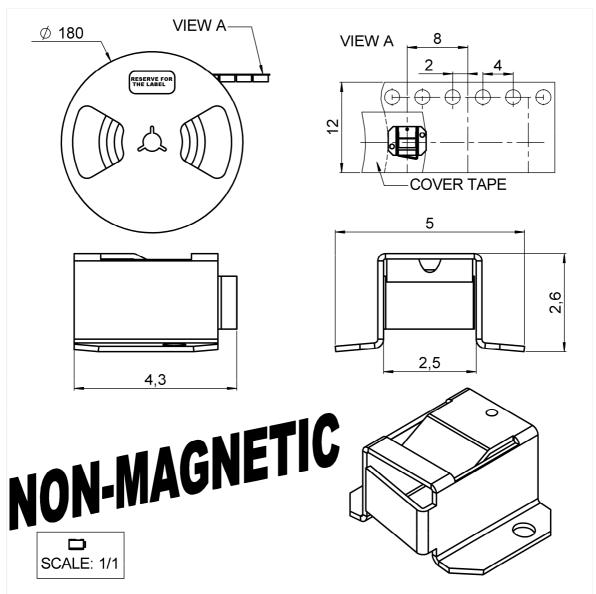
REEL OF 100

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Series: UMP



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (μm)	
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	BERYLLIUM COPPER	- TINTIN	

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PACKAGING

Standard	Unit	Other
100	Option W	Contact us

SPECIFICATION

PAQP-VOR-017

ELECTRICAL CHARACTERISTICS

Impedance 50 Ω

Frequency 0-6 GHz

VSWR 1.05 + 0,0300 x F(GHz) Maxi Insertion loss NA $\sqrt{F(GHz)}$ dB Maxi RF leakage - (NA - F(GHz)) dB Maxi Voltage rating 100 Veff Maxi

 Voltage rating
 100 Veri Maximal

 Dielectric withstanding voltage
 350 Veff mini

 Insulation resistance
 1000 MΩ mini

ENVIRONMENTAL

Operating temperature -40/+55 ° C

Hermetic seal **NA** Atm.cm3/s

Panel leakage NA

OTHER CHARACTERISTICS

Assembly instruction NA

Others:

magnetic field distorsion

< to 0.5 ppm at 10 mm at Bo=1.5 Tesla

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end - N mini
Axial force – Opposite end - N mini
Torque - N.cm mini

Recommended torque

Mating - N.cm
Panel nut - N.cm

Mating life 100 Cycles mini

Weight **0,0500** g

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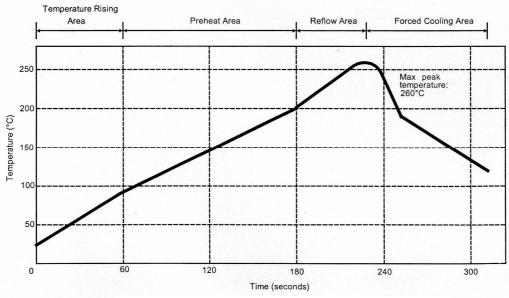
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SOLDER PROCEDURE OF UMP RECEPTACLE IN INDUSTRIAL ENVIRONMENT

- 1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven. Below please find, the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged.
- 5. Verification of solder joints and position of the component by visual inspection.

NOTE : THE UMP RECEPTACLE AND THE UMP PLUG MUST NOT BE MATED BEFORE COMPLETION OF THIS PROCEDURE.



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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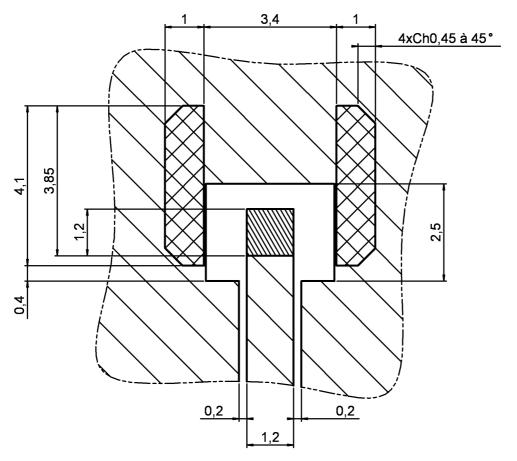
UMP SERIES INFORMATION

PCB

COPLANAR LINE

Ground and signal are on the same side

Thickness of PCB:1 mm



 $18 \mu m Cu mini + 7 to 9 \mu m Sn$

18 μm Cu mini + 7 to 9 μm Sn

lΥ

Ŋ Ground + varnish

The material of PCB is glass-epoxy Composite. (Er=4.8)

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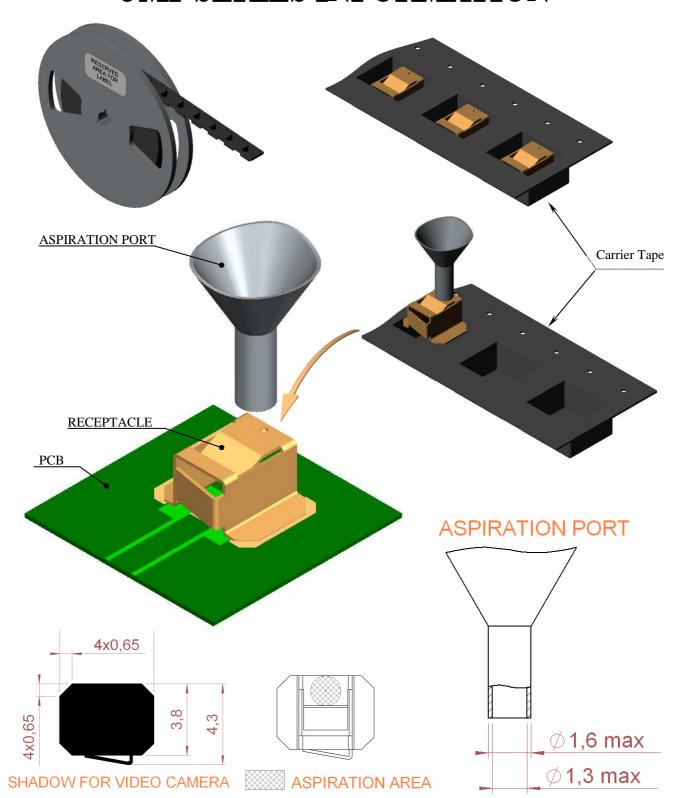


REEL OF 100

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UMP SERIES INFORMATION



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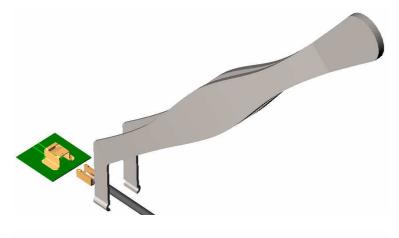


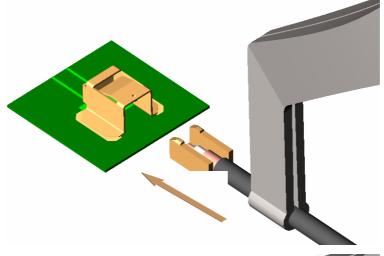
REEL OF 100

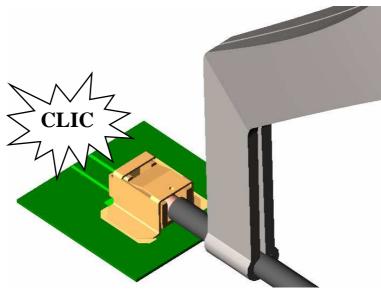
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UMP CONNECTING NOTE







Do not push Over the "CLIC"

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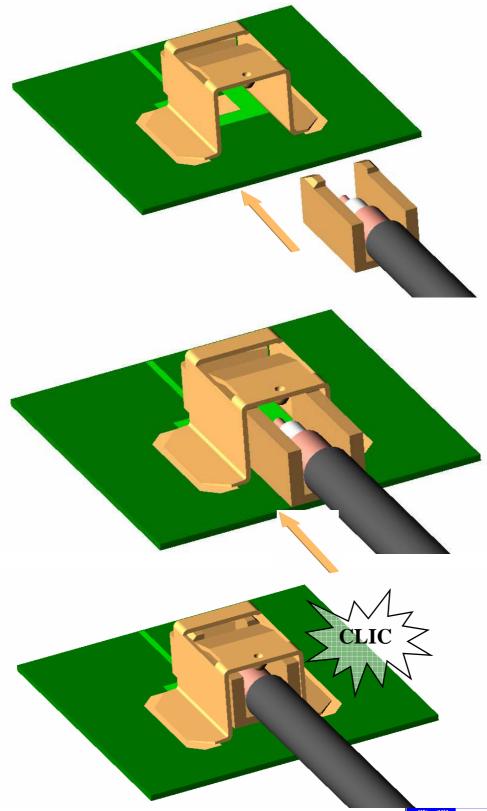


REEL OF 100

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UMP CONNECTING NOTE



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In the effort to improve our products, we reserve the right to make changes judged to be

necessary.

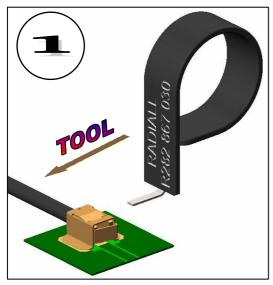


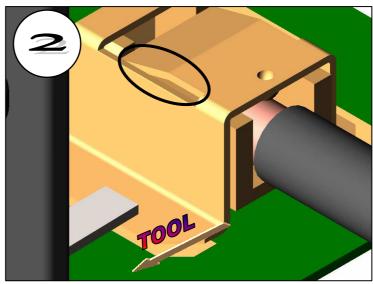
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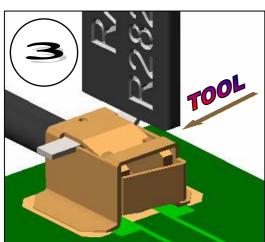
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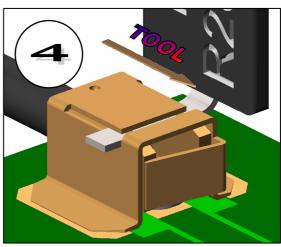
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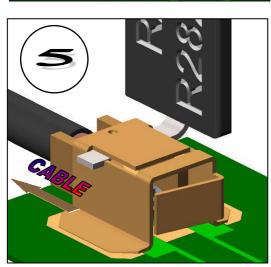
UMP DISCONNECTING NOTE

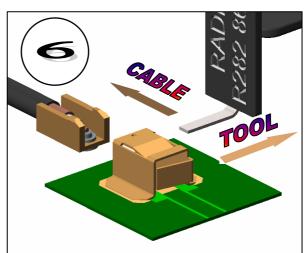












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